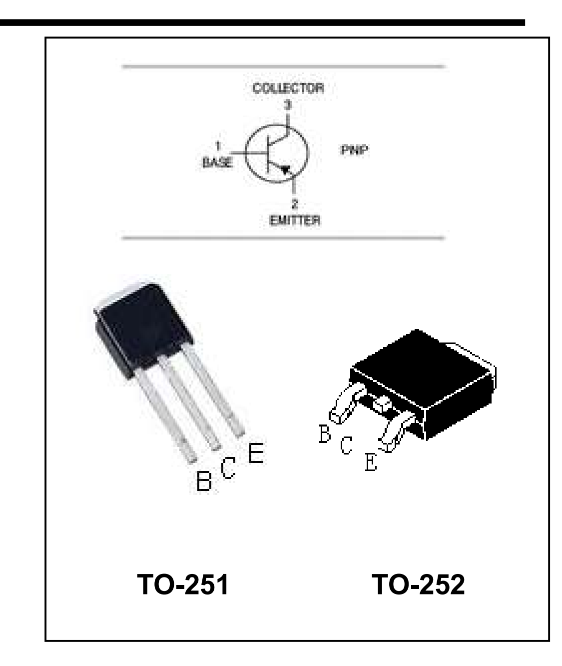


PNP Silicon Epitaxial Planar Transistor B772

FEATURES

Lead-free

- Low speed switching.
- Low saturation voltage.
- Excellent h_{FE} linearity and high h_{FE}.
- Complementary: D882.



APPLICATIONS

- Audio frequency power amplifier.

MAXIMUM RATING @ Ta=25℃ unless otherwise specified

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage	-40	V
V_{CEO}	Collector-Emitter Voltage	-30	V
V_{EBO}	Emitter-Base Voltage	-5	V
I_C	Collector Current -Continuous	-3	A
P_C	Collector Dissipation	1.25	W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient Air	100	℃/W
T_j, T_{stg}	Junction and Storage Temperature	-55 to +150	℃

PNP Silicon Epitaxial Planar Transistor B772

ELECTRICAL CHARACTERISTICS @ Ta=25℃ unless otherwise specified

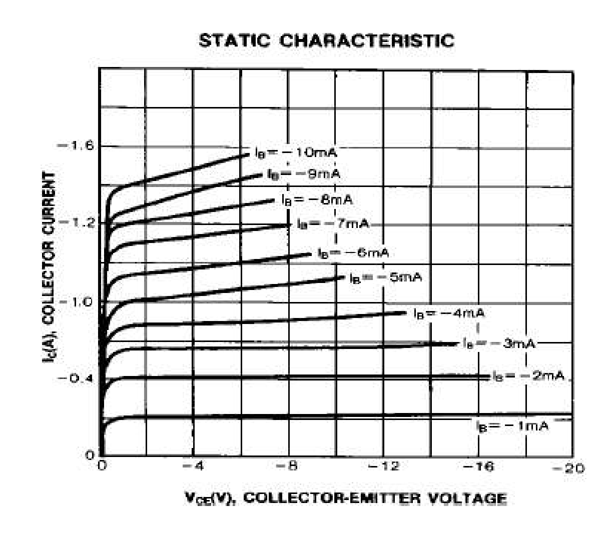
Parameter	**Symbol**	**Test conditions**	**MIN**	**TYP**	**MAX**	**UNIT**
Collector-base breakdown voltage	$V_{(BR)CBO}$	I_C=-100μA,I_E=0	-40			V
Collector-emitter breakdown voltage	$V_{(BR)CEO}$	I_C=-10mA,I_B=0	-30			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	I_E=-100μA,I_C=0	-6			V
Collector cut-off current	I_{CBO}	V_{CB}=-40V,I_B=0			-1	μA
Collector cut-off current	I_{CEO}	V_{CB}=-30V,I_E=0			-1	μA
Emitter cut-off current	I_{EBO}	V_{EB}=-6V,I_C=0			-1	μA
DC current gain	h_{FE}	V_{CE}=-2V,I_C=-1A V_{CE}=-2V,I_C=-20mA	60 30	160 220	400	
Collector-emitter saturation voltage	$V_{CE(sat)}$	I_C=-2A, I_B= -0.2A		-0.3	-0.5	V
Base-emitter saturation voltage	$V_{BE(sat)}$	I_C=-2A, I_B= -0.2A		-1.0	-2.0	V
Transition frequency	f_T	V_{CE}=-5V, I_C= -0.1A		80		MHz
Collector output capacitance	C_{ob}	V_{CB}=-10V,I_E=0,f=1MHz		55		pF

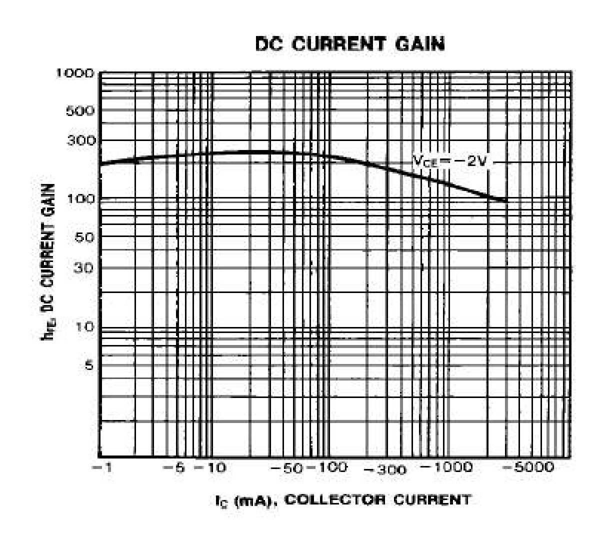
CLASSIFICATION OF h_{FE}

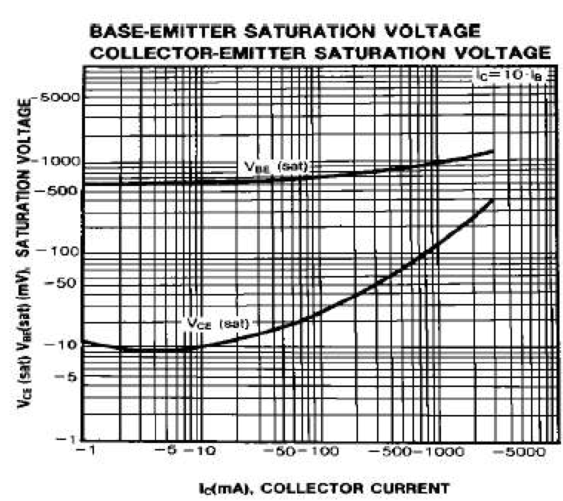
Rank	R	O	Y	G
Range	60-120	100-200	160-320	200-400

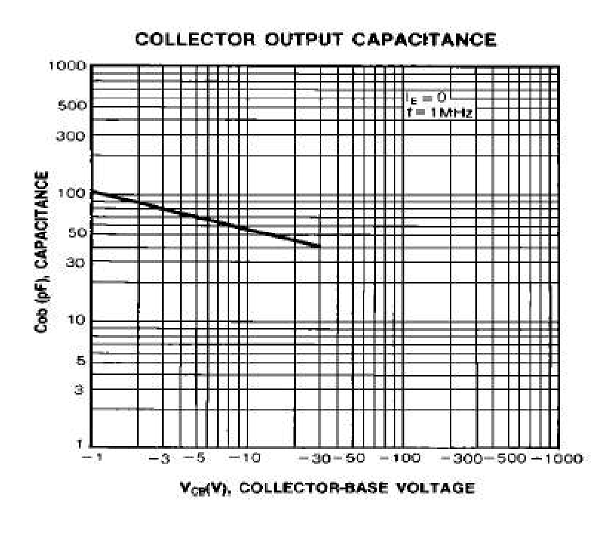
PNP Silicon Epitaxial Planar Transistor **B772**

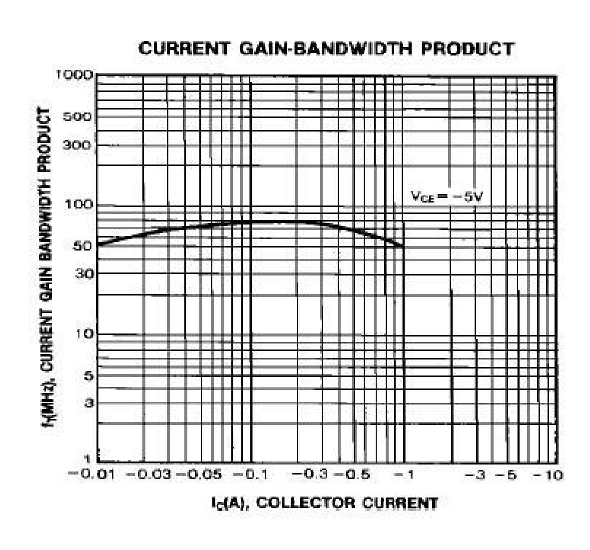
TYPICAL CHARACTERISTICS @ Ta=25℃ unless otherwise specified

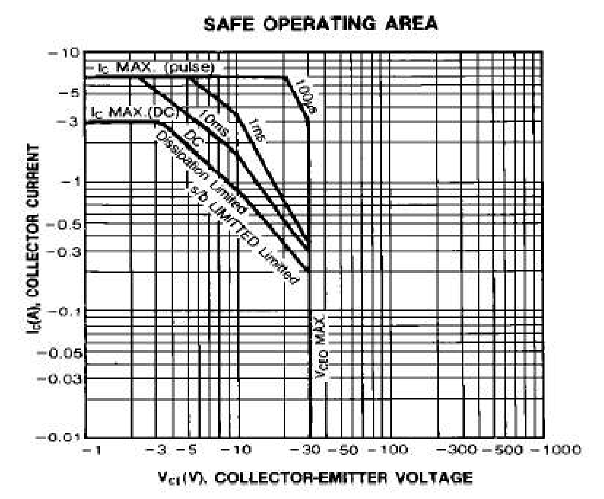










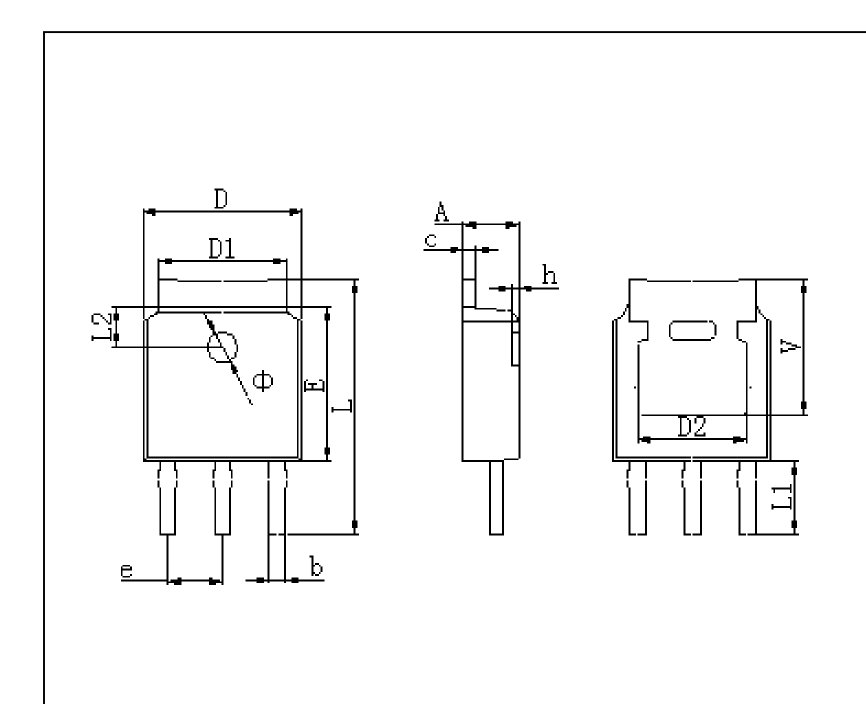


PNP Silicon Epitaxial Planar Transistor B772

PACKAGE OUTLINE

Plastic surface mounted package

TO-251

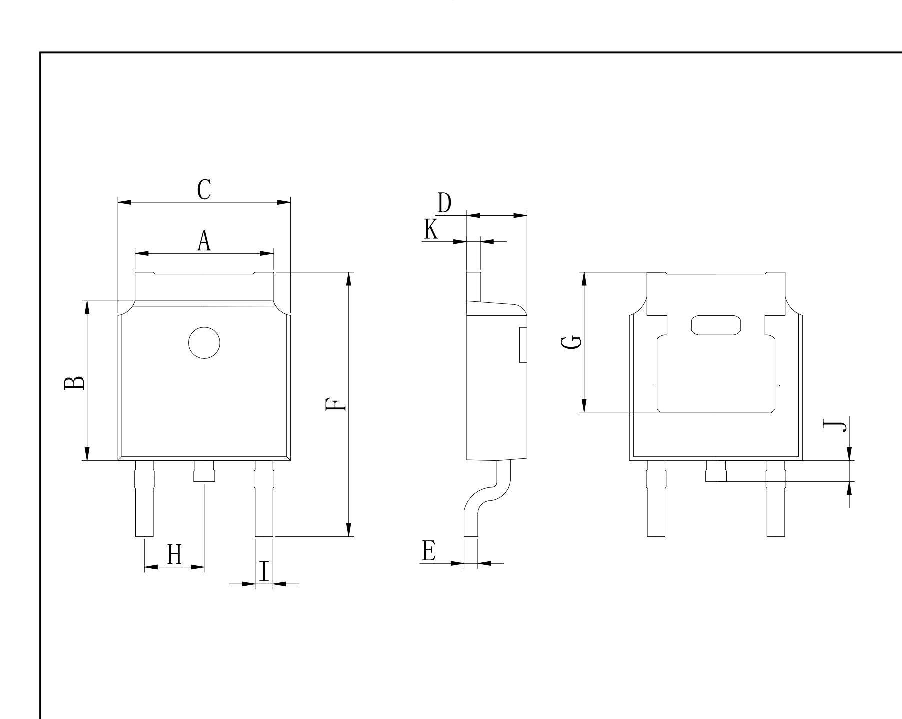


TO-251		
A	2.200	2.400
b	0.500	0.700
c	0.460	0.580
D	6.500	6.700
D1	5.100	5.460
D2	4.830 Typ.	
E	6.000	6.200
e	2.186	2.386
L	12.000	12.600
L1	5.100 Typ.	
L2	1.400	1.700
Φ	1.100	1.300
h	0.000	0.300
V	5.350 Typ.	
All Dimensions in mm		

PACKAGE OUTLINE

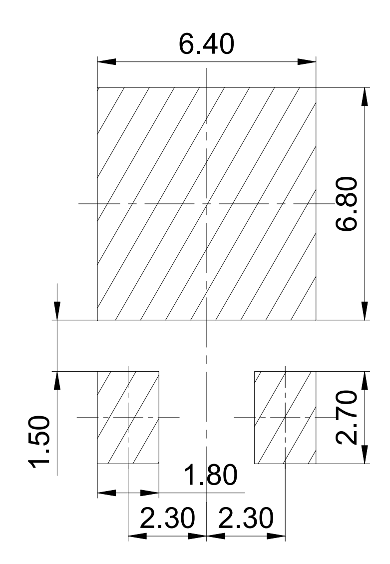
Plastic surface mounted package

TO-252



TO-252		
A	4.95	5.59
B	5.40	6.63
C	6.05	7.10
D	2.20	2.40
E	0.40	0.61
F	8.80	10.60
G	5.35 Typ.	
H	1.98	2.59
I	0.50	0.90
J	0.50	1.20
K	0.45	0.89
All Dimensions in mm		

SOLDERING FOOTPRINT



Unit:mm

PACKAGE INFORMATION

Device	Package	Shipping
B772	TO-251/252	80PCS/Tube
	TO-252	2500PCS/Tape&Reel